

CLAIMS

What is claimed is:

1. A heat sink module, comprising:
 - a heat dissipation pad being flexible and a cambered shape, wherein the heat dissipation pad
5 being between a heat conducting plate and a CPU.
2. The heat sink module according to claim 1, further comprises:
 - a base with a fixing device, the fixing device fixes the heat sink module in a portable electronic device, wherein one side of the heat dissipation pad is positioned to one side of the base.
10 3. The heat sink module according to claim 2, wherein the portable electronic device is a notebook computer.
 4. The heat sink module according to claim 2, wherein the portable electronic device is a tablet PC.
 5. The heat sink module according to claim 2, wherein the portable electronic device is a personal digital assistant (PDA).
15 6. The heat sink module according to claim 1, wherein the heat conducting plate is fixed to the base and against the heat dissipation pad tightly when the heat sink module installed in a portable electronic device.
 7. The heat sink module according to claim 1, further comprises:
 - 20 a heat pipe, which one end connects the heat conducting plate to bring away heat accumulated at the heat conducting plate.
 8. The heat sink module according to claim 7, further comprising:
 - a plurality of heat dissipation fins connect another end of the heat pipe.
25 9. The heat sink module according to claim 8, further comprising:
 - a fan is provided beside the plurality of heat dissipation fins.
 10. The heat sink module according to claim 1, wherein the heat dissipation pad has a fixing portion.

11. The heat sink module according to claim 1, wherein the heat dissipation pad has a flexible portion.
12. The heat sink module according to claim 1, wherein the heat dissipation pad is in a shape of a plate.

5 13. The heat sink module according to claim 11, wherein the flexible portion of the heat dissipation pad is in a shape of a cambered plate.

14. The heat sink module according to claim 1, wherein the heat dissipation pad is made of heat dissipation material.

15. The heat sink module according to claim 1, wherein heat dissipation paste is applied between
10 a heat conducting plate and the heat dissipation pad.